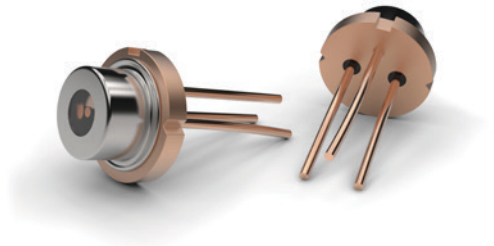


Laser Diode Bonding

LASER DIODE BONDING	DIE ATTACH	LOCTITE® ABLESTIK® ABP 8068TA	LOCTITE ABLESTIK ABP 8068TB
		LOCTITE ABLESTIK 84-1LMI	LOCTITE ABLESTIK 84-1LMISR4
		LOCTITE ABLESTIK 8910T	LOCTITE ABLESTIK 84-3



PRODUCT	TECHNOLOGY	APPLICATION	KEY ATTRIBUTES	VISCOSITY (cP)	GLASS TRANSITION TEMPERATURE, T _g (°C)	THERMAL CONDUCTIVITY (W/m•K)	CURE TYPE	CURE SCHEDULE
LOCTITE ABLESTIK ABP 8068TA	Semi-Sintering	Conductive Adhesive	<ul style="list-style-type: none"> One component Dispensable Printable low temp cure semi-sintering paste High lead solder replacement High thermal conductivity High reliability 	9,000	N/A	110	Heat	<p>For the die size < 5 x 5 mm: 20 min. ramp from 25°C to 130°C, hold for 30 to 60 min.; 15 min. ramp to 200°C hold for 60 min. in N₂ or air oven</p> <p>For die size > 5 x 5 mm: 20 min. ramp from 25°C to 130°C, hold for 120 min.; 15 min. ramp to 200°C, hold for 60 min. in N₂ or air oven</p>
LOCTITE ABLESTIK ABP 8068TB	Semi-Sintering	Conductive Adhesive	<ul style="list-style-type: none"> No resin bleed-out One component Good workability Printable low temp cure semi-sintering paste Good electrical stability High thermal stability High reliability Solder replacement 	11,500	25	110	Heat	<p>For die size , < 5 x 5 mm: 20 min. ramp from 25°C to 130°C, hold for 30 – 60 min.; 15 min. ramp to 200°C, hold for 120 min. in N₂ or air oven.</p> <p>For die size > 5 x 5 mm: 20 min. ramp from 25°C – 130°C, hold for 30 – 60 min.; 15 min. ramp to 200°C, hold for 120 min. in N₂ or air over</p>
LOCTITE ABLESTIK 84-1LMI	Epoxy	Die-Attach	<ul style="list-style-type: none"> Conductive Low outgassing Low bleed Meets MIL-STD-883 Method 5011 requirements 	30,000	103	2.4	Heat	60 min. at 150°C
LOCTITE ABLESTIK 84-1LMISR4	Epoxy	Die-Attach	<ul style="list-style-type: none"> Conductive Excellent dispensability Minimal tailing and stringing 	8,000	120	2.5	Heat	60 min. at 175°C
LOCTITE ABLESTIK 8910T	BMI Hybrid	Die-Attach	<ul style="list-style-type: none"> Non-conductive High thermal conductivity High reliability 	22,000	30	1.3	Heat	30 min. ramp to 175°C + 15 min. at 175°C
LOCTITE ABLESTIK 84-3	Epoxy	Die-Attach	<ul style="list-style-type: none"> Non-conductive Solvent free formulation Long work life 	50,000	85	0.8	Heat	60 min. at 150°C